

## 7.8 COL License Information

### 7.8.1 Effects of Station Blackout on the HVAC

A temperature heat rise analysis shall be provided by the COL applicant for the station blackout (SBO) scenario applied to the control room on consideration of the environmental temperatures unique to the plant location (see Chapter 20, NRC Question 420.14).

### 7.8.2 Electrostatic Discharge on Exposed Equipment Components

The response to NRC Question 420.90 provides recommendations for limiting the effects of electrostatic discharge (ESD) at keyboards, keyed switches and other exposed equipment. The COL applicant shall provide assurance that the grounding and shielding techniques are consistent with these recommendations, or provide an acceptable alternative plan for controlling ESD (see Chapter 20, NRC Question 420.90).

### 7.8.3 Localized High Heat Spots in Semiconductor Materials for Computing Devices

*[Tables 10 and 11 of DCD/Introduction identify the commitments to use the response to Q420.92, which, if changed, requires NRC Staff review and approval prior to implementation. The applicable portions are italicized on the response to Q420.92 in Subsection 20.3.8.]\**

The response to NRC Question 420.92 provides recommendations for limiting high current densities which could result in localized heat spots in semiconductor materials used in computing devices. The COL applicant shall provide assurance that these recommendations are followed, or an acceptable alternative is presented, by the selected equipment vendor(s). To ensure that adequate compensation for heat rise is incorporated into the design, a thermal analysis shall be performed at the circuit board, instrument and panel design stages.

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\* See Section 3.5 of DCD/Introduction.